

PATENT

## PENDING CLAIMS

Please amend claims 1 and 12 and cancel claims 13 and 15.

1. (currently amended) A method for making a high pin-count die, comprising the steps of :
  - providing a substrate;
  - forming a die attach area onto the substrate for mounting a die, the die having at least one bond pad;
  - locating at least one bond island onto the substrate; and
  - connecting the bond pad to the bond island with a wire bond; and
  - connecting a plurality of solder balls to the at least one bond island, the plurality of solder balls being located inwardly from an edge of the substrate,  
wherein at least one redundant solder ball is used to form a path for the inner solder balls connected to bond islands to be electrically plated.
2. (original) The method of claim 1, further comprising the step of encapsulating the die.
3. (original) The method of claim 1, further comprising forming a trace between the bond island and a package lead located on the substrate.
4. (original) The method of claim 3, wherein the package lead is a solder ball included in a ball grid array (BGA).
5. (original) The method of claim 3, wherein the package lead is a land included in a land grid array (LGA).
6. (original) The method of claim 1, further comprising the step of depositing a bond finger onto the substrate.

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7. (original) The method of claim 6, further comprising the step of bonding a wire between the bond finger and the bond pad.

8. (original) The method of claim 6, further comprising the step of forming a trace between the bond finger and a package lead.

9. (original) The method of claim 8, wherein the package lead is a solder ball included in a ball grid array (BGA).

10. (original) The method of claim 8, wherein the package lead is a land in a land grid array (LGA).

11. (original) The method of claim 1, further comprising the step of forming a plurality of die attach areas on the substrate for mounting a plurality of die.

12. (currently amended) A method for providing an area array package, comprising the steps of:

providing a substrate;

attaching one or more die to the substrate;

wire bonding the die to the substrate; [and]

encapsulating the wires and die on the substrate; and

coupling a plurality of solder balls to at least one of a plurality of bond islands located on the substrate.

wherein at least one redundant solder ball is used to form a path for the inner solder balls connected to bond islands to be electrically plated.

13. (canceled)

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14. (currently amended) The method of claim [[13]] 12, further comprising the step of coupling a plurality of bond fingers located on the substrate to the solder balls or the bond islands.

15. (canceled)